深圳市炬烜科技有限公司
CHIP SUN TECHNOLOGY CO., LTD.

APPROVAL SHEET

RoHS Compliant

(Seam Type)

CUSTOMER：	MICROS sp.j. W.Kedra i J.Lic
DESCRIPTION：	SMD5032 20.000MHz Quartz Crystal Resonator
MANUFACTURER PART NO.：	FTX20.000M20SM5S-20/20BEW
CUSTOMER PART NO：	
USED IN MODEL：	
REVISION	A1

承　　认　　APPROVAL		
工程部 TECHNOLOGY DEPT.	品质部 QUALITY DEPT.	采购部 PURCHASING DEPT.

Date: March 22, 2023

深圳市炬烜科技有限公司
CHIP SUN TECHNOLOGY CO.，LTD
地址 ADD: 深圳市龙华新区大浪腾龙路淘金地电子商务孵化基地 B 座 206
Rm. Rm 206, Tower B, Taojindi Building, Tenglong Road, Dalang Street, Longhua New District, Shenzhen, China
电话 TEL: 86-755-83458796　传真 FAX: 86-755-83459818
网址 WEB ADD: http://www.chinchipsun.com
E-MAIL: sales01@chinachipsun.com

Rev	Revise page	Revise contents	Date	Ref.No.	Reviser
A1	ALL	Initial released		N/A	DavidJiang

1. QUARTZ CRYSTAL UNIT SPECIFICATION

1.1 Nominal Frequency :	20.000MHz
1.2 Holder type :	FTX531S（SMD5032 SEAM）
1.3 Mode of oscillation:	Fundamental
1.4 Frequency tolerance:	±20ppm at 25℃±3℃
1.5 Equivalent resistance:	50 ohms max
1.6 Operating temperature range:	-20℃ To +70℃
1.7 Storage temperature range:	-55℃ To +125℃
1.8 Frequency Stability:	±20ppm at -20℃ To +70℃
1.9 Loading capacitance (CL) :	20 pF
1.10 Drive level:	100 uW Typical（300 uW max）
1.11 Shunt Capacitance:	5.0pF max
1.12 Insulation resistance :	More than 500MΩ at DC 100V
1.13 Circuit:	Measured in HP/E5100A,S&A 250B
1.14 Aging:	±3 ppm Max (+25℃ 1st Year)
1.15 Dimensions and marking	Refer to page.3
1.16 Emboss carrier tape & reel	Refer to page.5 and page.6

1.17 Note:

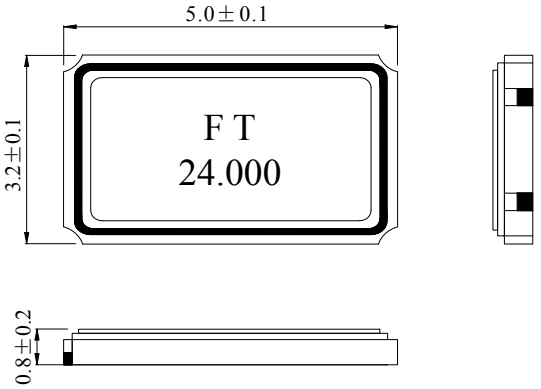
Standard atmospheric conditions

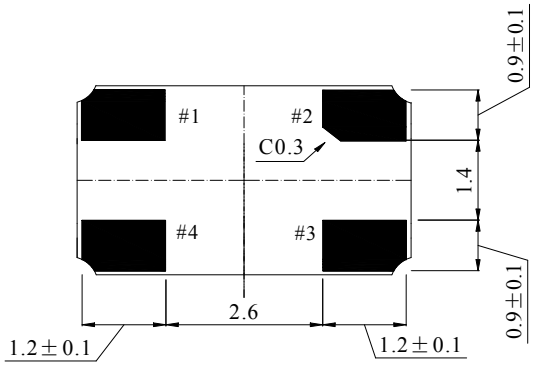
Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : 25±3℃

Relative humidity : 40%~70%

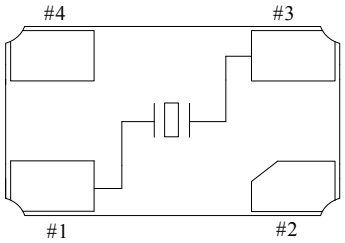
2. FTX531S MARKING & DIMENSIONS



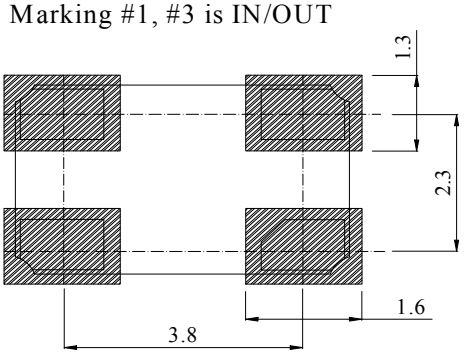


Marking #2, #4 is connected with metal c

Marking #1, #3 is IN/OUT



<TOP VIEW>



Recommended Solder Pad Layout:

*Marking should be printed as following:

Logo, Nominal Frequency

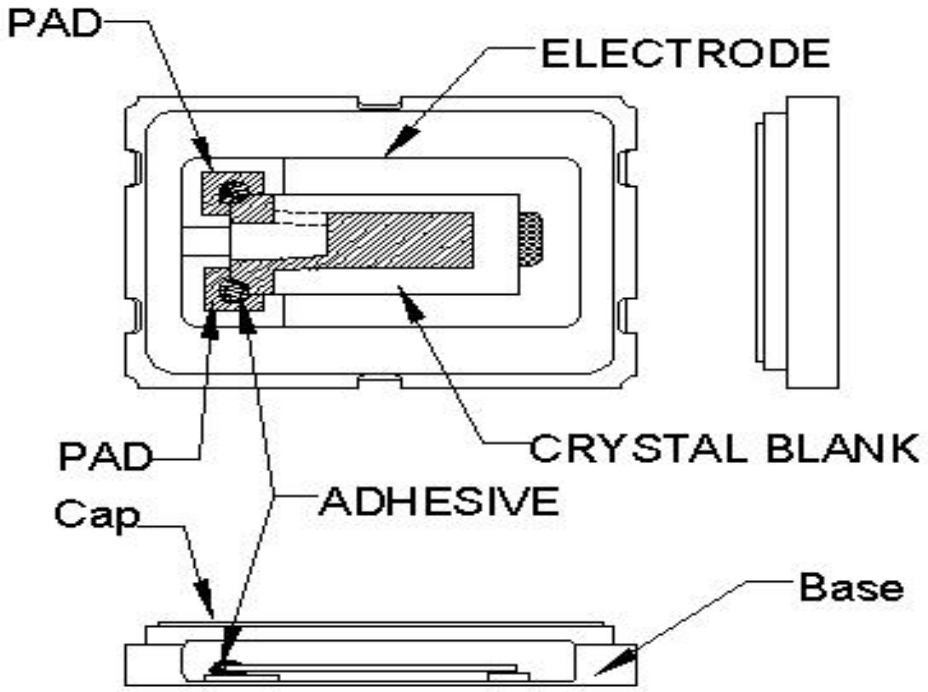
*Manufacturing Logo: FT

*Nominal frequency = 3 number after decimal point MAX.

(ex. 12.000 MHz → 12.000)

Marking: Laser marking

3. INSIDE STRUCTURE

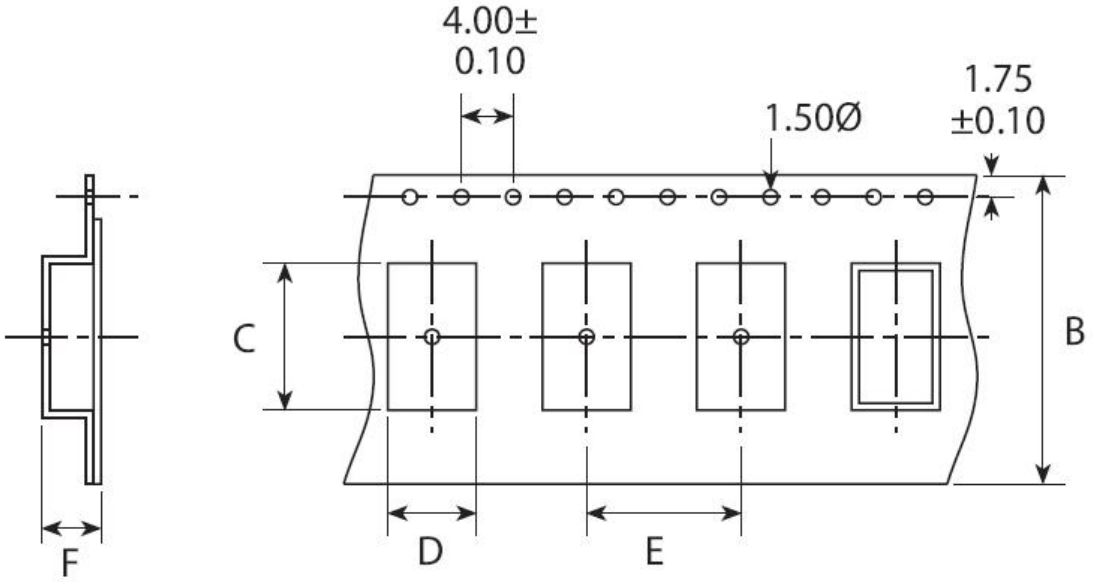


Reference drawing

Base: Alumina Ceramic (Al_2O_3) Metallized Pad: W Ni Plating Au Plating
Cap: Fe-Ni
(3) Crystal Enclosure Seal: Seal Seam
(4) Crystal Blank Rectangular At-Cut Quartz Crystal Blank
(5) Adhesive Silver Conductive Polyimide Resin
(6) Electrode Ag
(7)PAD Alumina Ceramic (W. Ni. Au)

4. FTX531S EMBOSS CARRIER TAPE & REEL

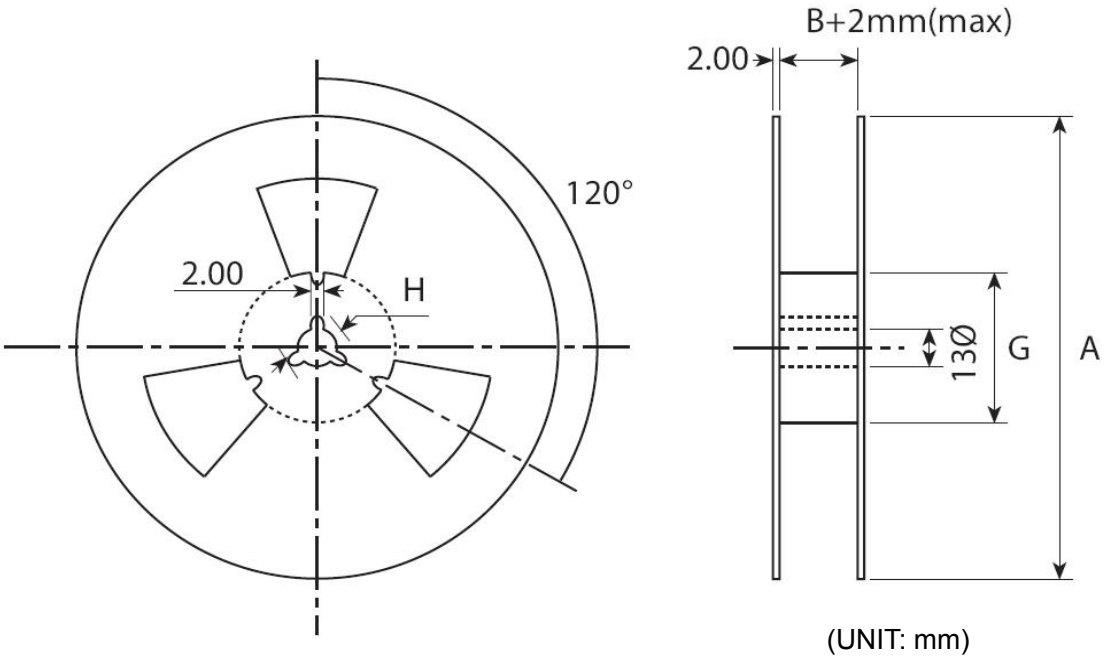
a.) Dimensions of Carrier Tape



	A	B	C	D	E	F	G
SMD5032	178±2.0	12.0±0.3	5.40±0.10	3.60±0.10	8.0±0.1	1.1±0.1	60.5±1.0

(UNIT: mm)

b.) Dimensions of Reel



(UNIT: mm)

c.) Storage condition

Temperature: +40deg.C Max.

Relative Humidity: 80% Max.

d.) Standard packing quantity

1,000PCS / REEL

e.) Material of the tape

Tape	Material
Carrier tape	A – PET
Top tape	Polyester

f.) Label contents

.The type of product

.Our specification No.

.Your Part No.

.Lot No.

.Nominal Frequency

.Quantity

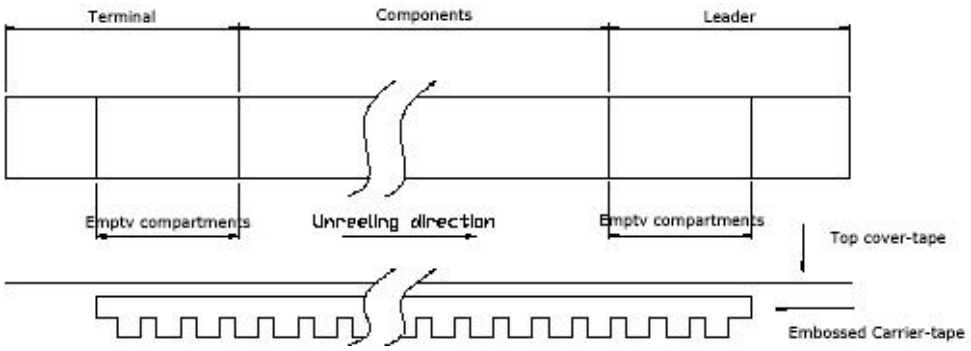
.Our Company Name

Sticks label for every reel.

PART NUMBER	
PO NO	
PR. NO:	
HOLDER TYPE	
FREQUENCY	
REMAKS	
QUANTITY	
FRONTER ELECTRONICS CO.,LTD.	

g.) Taping dimension

Leader	Cover-tape	The length of cover-tape in the leader is more than 400 mm including empty embossed area.
	Carrier-tape	After all products were packaged, must remain more than twenty pieces or 400 mm empty area, which should be sealed by cover-tape.
Terminal	Cover-tape	The tip of cover-tape shall be fixed temporary by paper tape and roll around the core of reel one round.
	Carrier-tape	The empty embossed area which are sealed by top cover-tape must remain more the 40 mm.



h.) Joint of tape

The carrier-tape and top cover-tape should not be jointed.

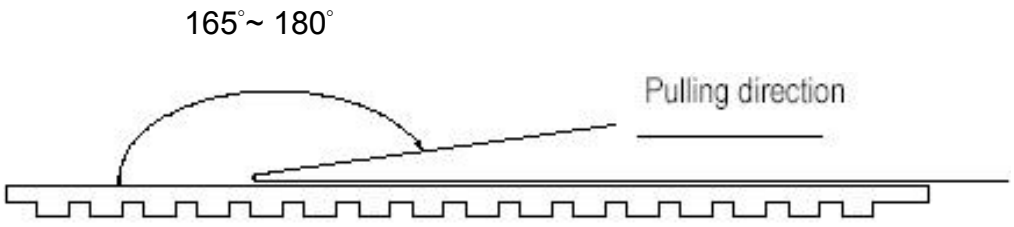
i.) Release strength of cover tape

It has to between 0.1N to 0.7N under following condition.

Pulling direction 165° to 180°

Speed 300mm/min.

Otherwise unless specified.



Other standards shall be based on JIS C 0806-1990.

5. Mechanical Endurance: Provided that measurement shall be carried out afterletting it alone in the room temperature for 1 hour min.

	Item	Conditions	Specifications
5.1	Drop	Method：fallen on the concrete (thickness is 3cm or more) Height：75 cm Direction：each direction of 3 mutually perpendicular (x、y、z) axis. Number of shocks：2 shocks in each direction	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
5.2	Vibration	Should be satisfied after supplying following vibration. (1)Vibration Frequency: 10~55Hz (2)Cycle: 1 to 2 Min. (3)Full Cycle: 1.5mm P-P. (4)Direction: X.Y.Z (5)Time: 2 Hours / Each Direction	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
5.3	Substrate Bending	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –1 Speed: 0.5 mm/sec Hours: 5 ± 1 sec Amount of substrate: 3 mm Max.	Without mechanical damage such as breaks. Without electrode peeling. Electrical characteristics shall be satisfied.
5.4	Adhesion	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –2 Weight: 10N Hours: 10 ± 1 sec	
5.5	Body strength	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –3 Weight: 10N Hours: 10 ± 1 sec	

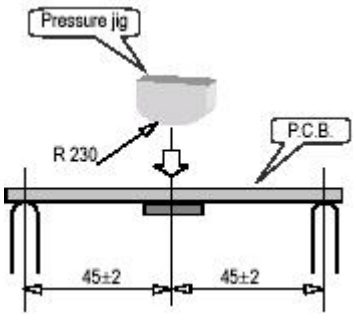


Fig-1

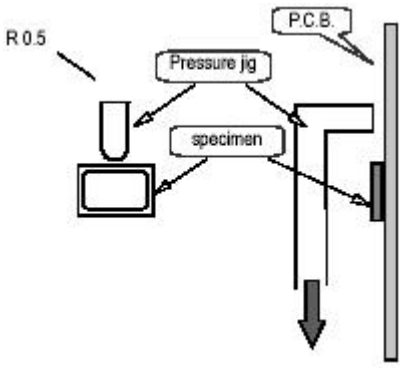


Fig-2

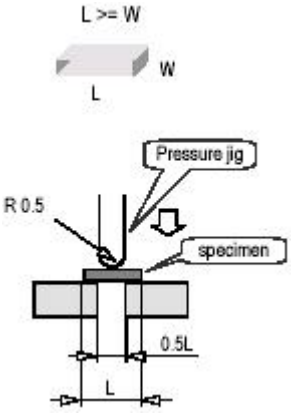
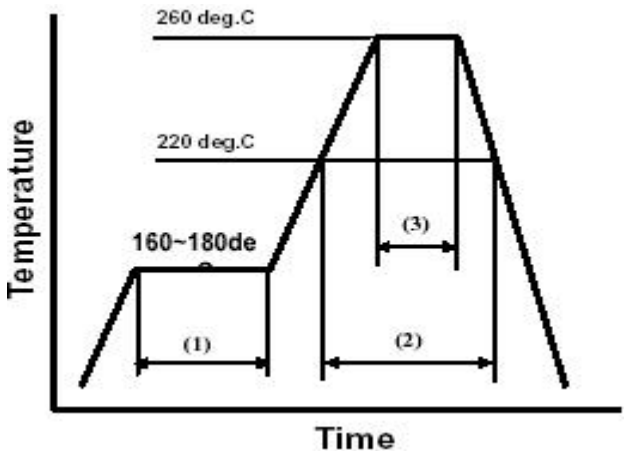


Fig-3

5.6	Seal	Less than 5.0 x 10^{-8} atm.cc/sec by Helium leak detector. Also, no serial bubble is observed by Fluorinate tests.	
5.7	Solder ability	3 sec Dip in 235℃±5℃ solder. (Use ROSIN type flux for solder.)	More than 90% of lead shall be covered by new solder.
5.8	Resistance to Soldering Heat	Run in Reflow Reflow soldering shall be allowed Only two(2) time. **Available for Lead Free Soldering**  (1) Preheat 160~180 deg.C 120sec. (2) Primary heat 220 deg.C 60sec. (3) Peak 260 deg.C 10sec. Max.	Freq. Drift ±10ppm Max. Resistance Drift ±20% Max.

6. Environmental Endurance: Provided that measurement shall be carried out afterletting it alone in the room temperature for 1 hour min.

	Item	Conditions	Specifications
6.1	Humidity	Should be satisfied after letting it alone at +60℃±2℃ in humidity of 90%～95% for 500 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.2	Storage in Low Temperature	Should be satisfied after letting it alone at -40℃±3℃ for 500 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.3	Storage in High Temperature	Should be satisfied after letting it alone at +85℃±3℃ for 500 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.4	Temperature Cycle	Should be satisfied after supplying the following temperature cycle (100 cycles). (Refer to Fig-4). Temperature shift from low to high, high to low shall be done in 1℃/min.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max

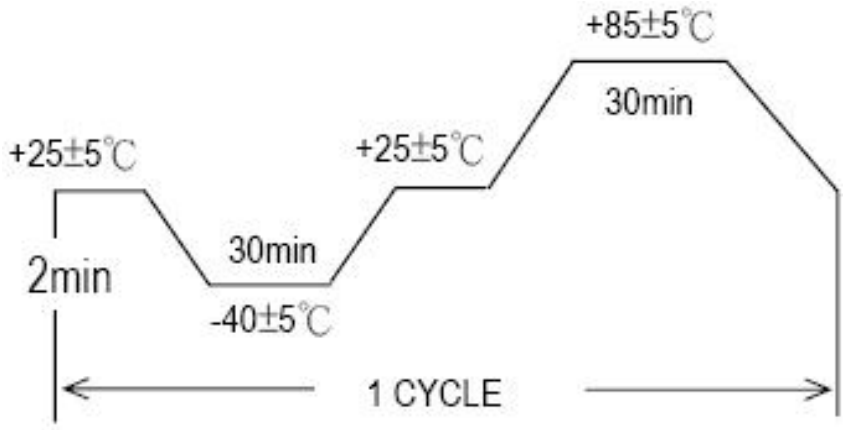


Fig-4